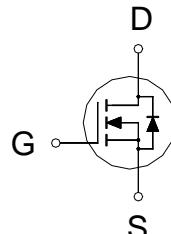


N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV _{DSS}	250V
R _{DSON} (MAX.)	1.7Ω
I _D	0.4A



Rg 100% Tested

Pb-Free Lead Plating & Halogen Free



ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNIT
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	0.4	A
		0.25	
Pulsed Drain Current ¹	I _{DM}	1.6	
Power Dissipation	P _D	1.25	W
		0.8	
Operating Junction & Storage Temperature Range	T _j , T _{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to- Ambient	R _{θJA}		100	°C / W

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, Unless Otherwise Noted)

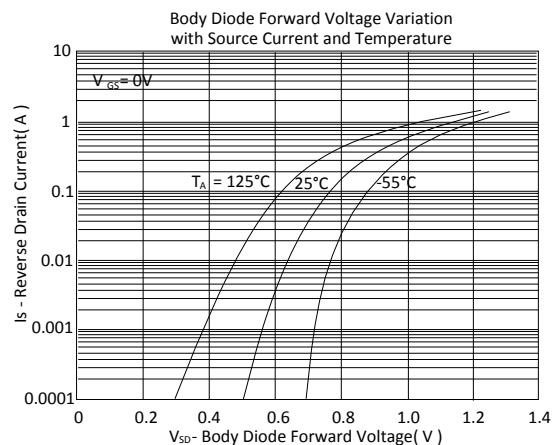
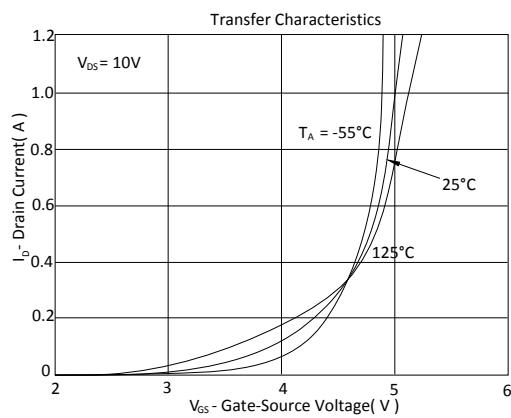
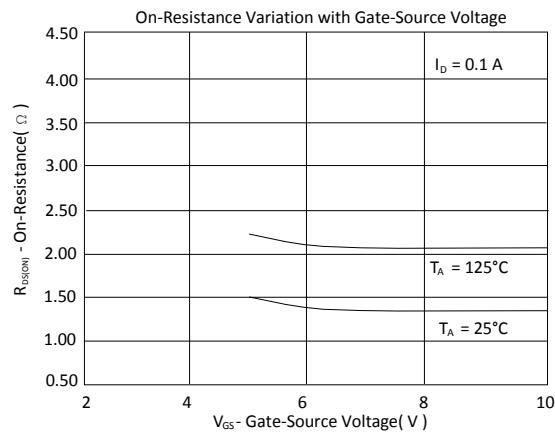
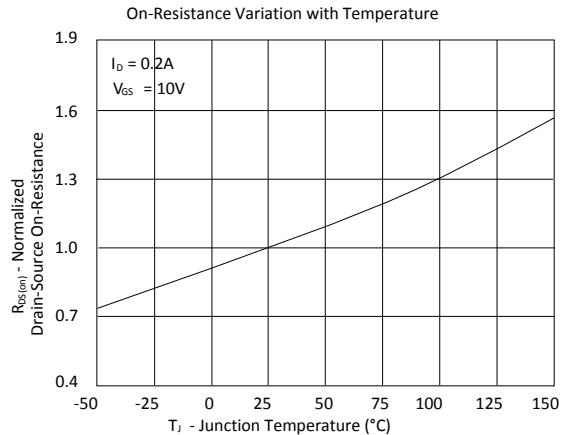
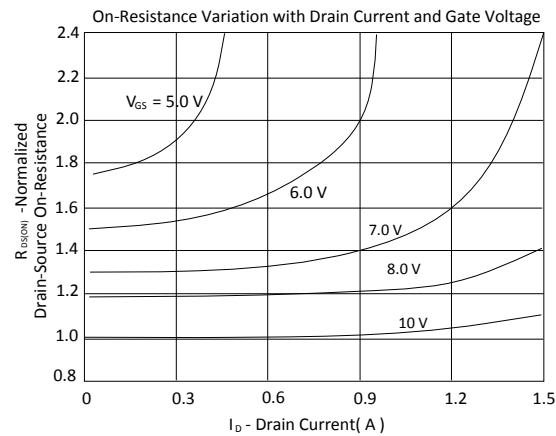
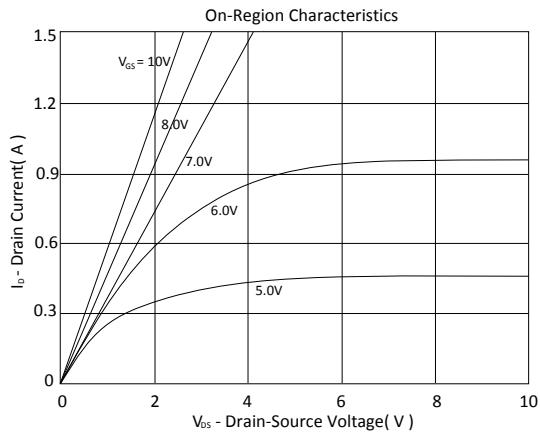
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 10\text{mA}$	250			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.0	2.0	3.0	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 200V, V_{GS} = 0V$			1	μA
		$V_{DS} = 200V, V_{GS} = 0V, T_J = 125^\circ\text{C}$			25	
On-State Drain Current ¹	$I_{D(\text{ON})}$	$V_{DS} = 10V, V_{GS} = 10V$	0.4			A
Drain-Source On-State Resistance ¹	$R_{DS(\text{ON})}$	$V_{GS} = 10V, I_D = 0.2\text{A}$		1.35	1.7	Ω
		$V_{GS} = 5V, I_D = 0.1\text{A}$		1.5	2.0	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 50V, I_D = 0.2\text{A}$		2.0		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1\text{MHz}$		680		
Output Capacitance	C_{oss}			15		pF
Reverse Transfer Capacitance	C_{rss}			13		
Gate Resistance	R_g	$V_{GS} = 15\text{mV}, V_{DS} = 0V, f = 1\text{MHz}$		3.0		Ω
Total Gate Charge ^{1,2}	Q_g	$V_{DS} = 200V, V_{GS} = 10V, I_D = 0.2\text{A}$		17.8		
Gate-Source Charge ^{1,2}	Q_{gs}			2.2		nC
Gate-Drain Charge ^{1,2}	Q_{gd}			4.4		
Turn-On Delay Time ^{1,2}	$t_{d(on)}$	$V_{DS} = 125V, I_D = 0.1\text{A}, V_{GS} = 10V, R_G = 6\Omega$		10		
Rise Time ^{1,2}	t_r			40		nS
Turn-Off Delay Time ^{1,2}	$t_{d(off)}$			12		
Fall Time ^{1,2}	t_f			20		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_c = 25^\circ\text{C}$)						
Continuous Current	I_S				0.5	A
Pulsed Current ³	I_{SM}				2	
Forward Voltage ¹	V_{SD}	$I_F = I_S, V_{GS} = 0V$			1.3	V

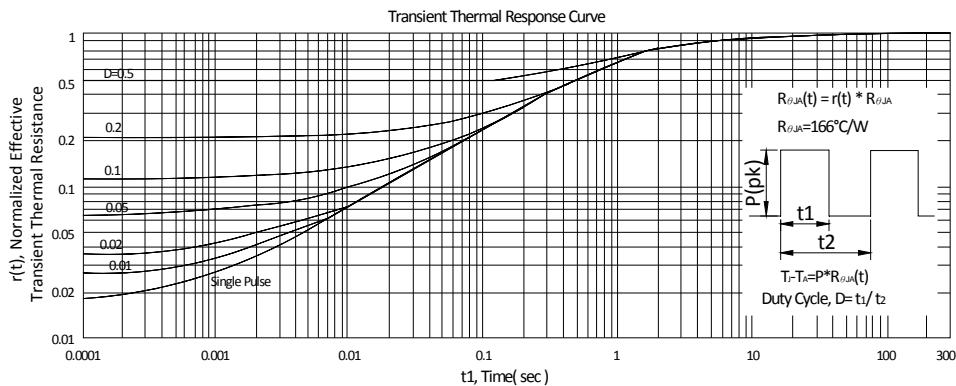
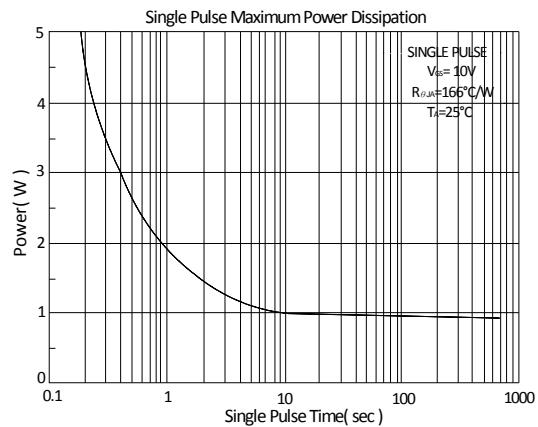
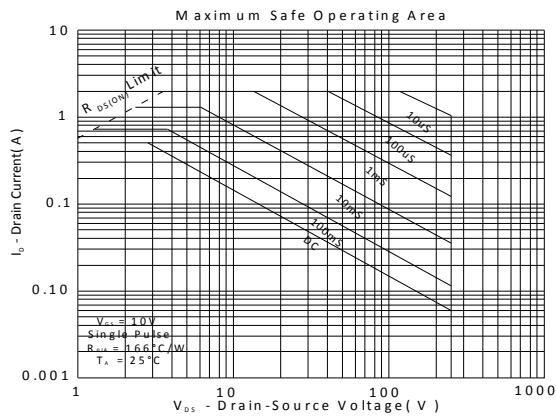
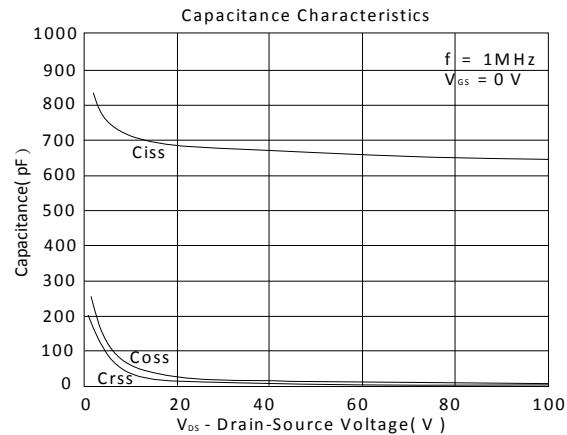
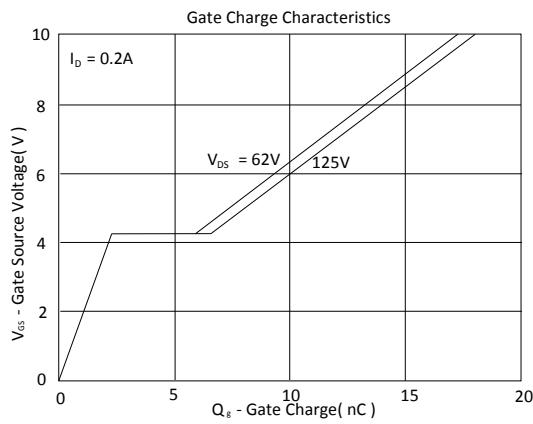
¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

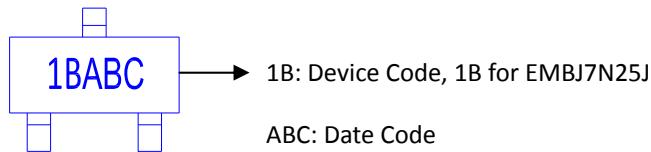
TYPICAL CHARACTERISTICS



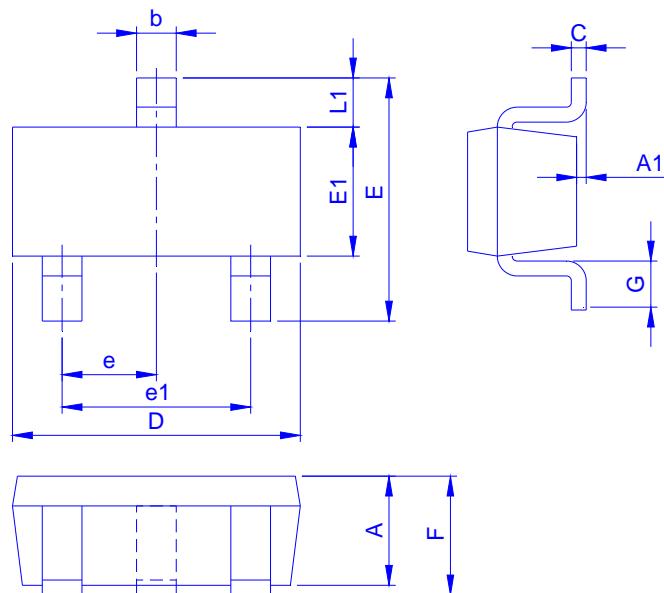


Ordering & Marking Information:

Device Name: EMBJ7N25J for SOT-23



Outline Drawing



Dimension in mm

Dimension	A	A1	A2	b	C	D	E	E1	e	e1	F	G	L1
Min.	0.7	0		0.35	0.1	2.8	2.6	1.5	0.9		0.8	0.3	0.55
Typ.						2.9	2.8	1.6	0.95	1.9			
Max.	1.12	0.1		0.5	0.2	3	3	1.7	1		1.2	0.6	0.65

Footprint

